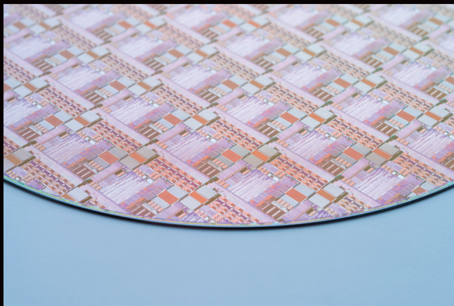
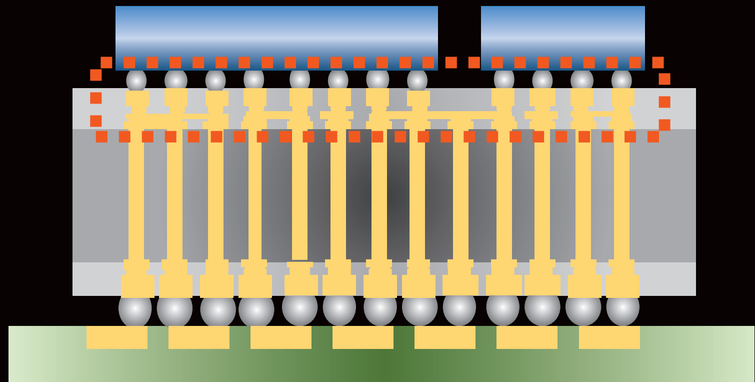
Acid copper plating additive
for ultra-micro patterning

TORYZA LCN FRV

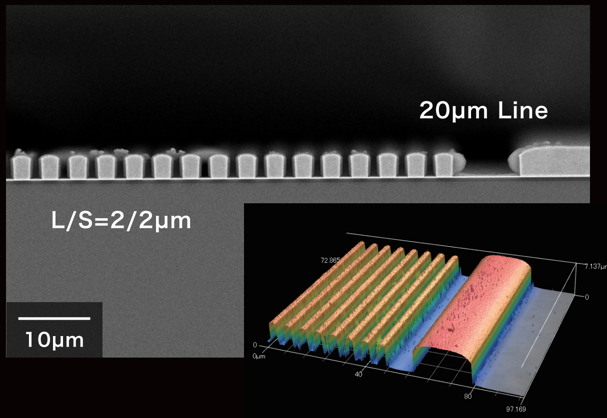
- Best for Redistribution layer (RDL) formation
- Reduce the influence by circuit design
- Uniform thickness, rectangle shape pattern is obtained

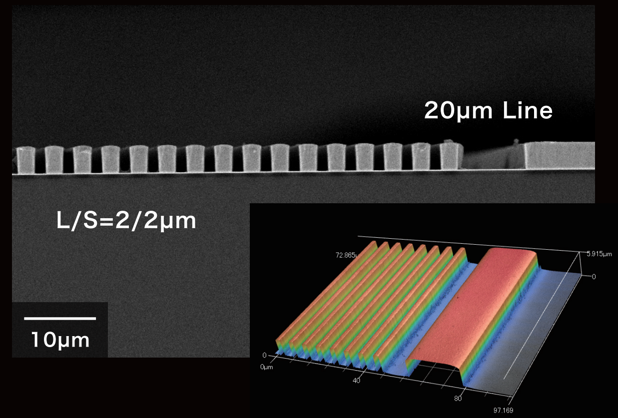




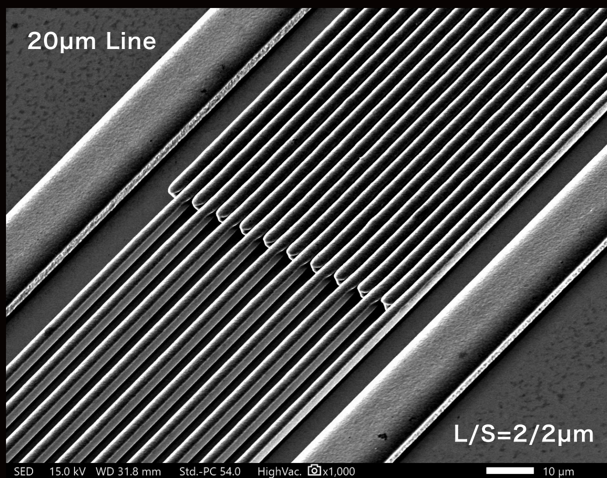
High film thickness uniformity

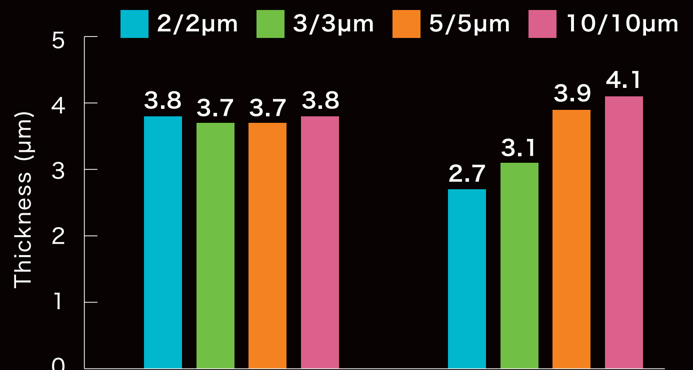
Conventional bath | **TORYZA LCN FRV**





Current density 3A/dm² surface thickness 4μm





TORYZA LCN FRV Conventional bath

Evaluation of film thickness uniformity in wiring design
(Current density 3A/dm²)